

SOT1331-1

plastic thermal enhanced thin shrink small outline package;
38 leads; body with 4.4 mm; lead pitch 0.5 mm; exposed die
pad

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	HTSSOP38
Package type industry code	HTSSOP38
Package style descriptive code	HTSSOP (thermal enhanced thin shrink small outline package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	21-9-2012

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	9.6	-	9.7	9.8	mm
E	package width	4.3	-	4.4	4.5	mm
A	seated height	[tbd]	-	[tbd]	1.1	mm
A ₂	package height	0.85	-	0.9	0.95	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	38	-	

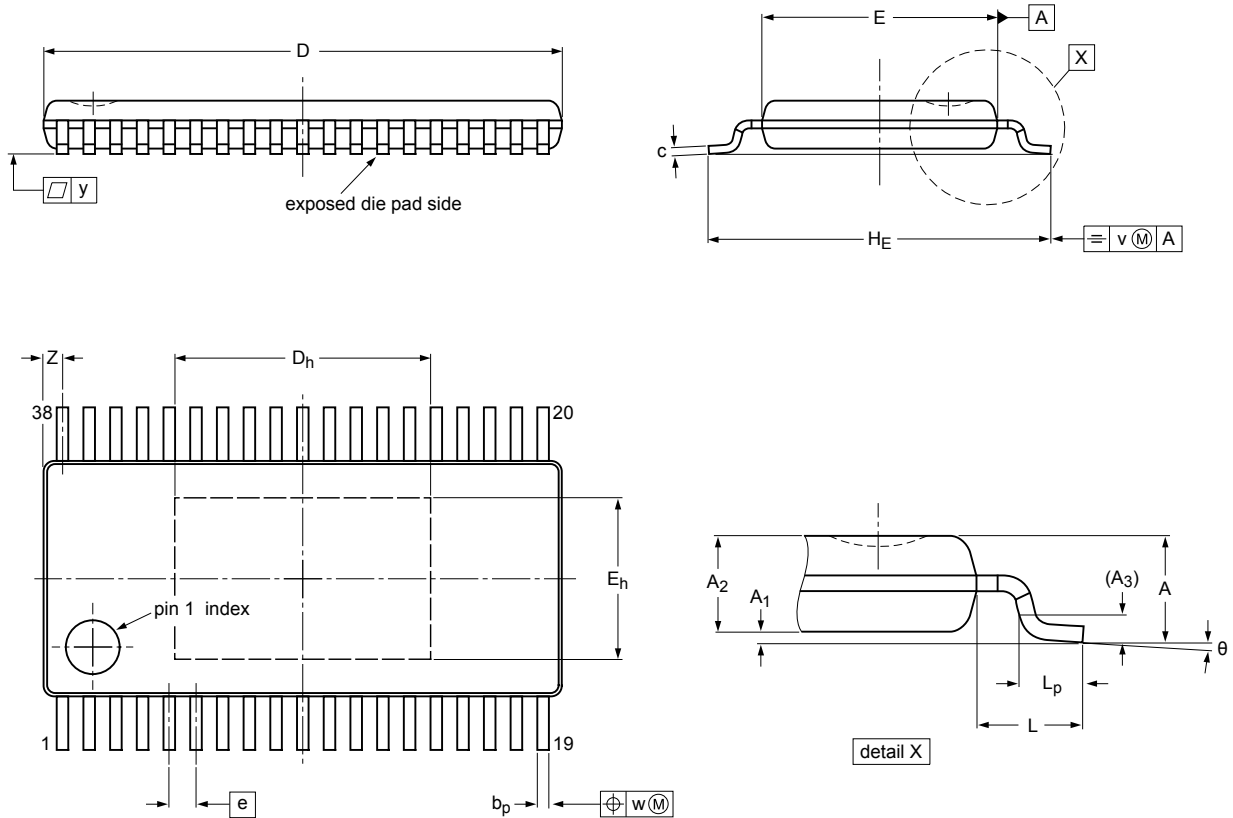


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2. Package outline

HTSSOP38: plastic thermal enhanced thin shrink small outline package; 38 leads; body with 4.4 mm; lead pitch 0.5 mm; exposed die pad

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Dimensions (mm are the original dimensions)

Unit ⁽¹⁾	A	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	D _h	E ⁽¹⁾	E _h	e	H _e	L	L _p	v	w	y	Z	θ
max	1.1	0.15	0.95		0.27	0.20	9.8	4.9	4.5	3.1								0.49	8°
nom		0.10	0.90	0.25	0.21	0.15	9.7	4.8	4.4	3.0	0.5	6.4	1.0	0.6	0.2	0.08	0.08	0.35	4°
min		0.05	0.85		0.17	0.09	9.6	4.7	4.3	2.9				0.5				0.21	0°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

sot1331-1_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1331-1					-12-07-30- 12-08-20

Fig. 1. Package outline HTSSOP38 (SOT1331-1)

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3. Soldering

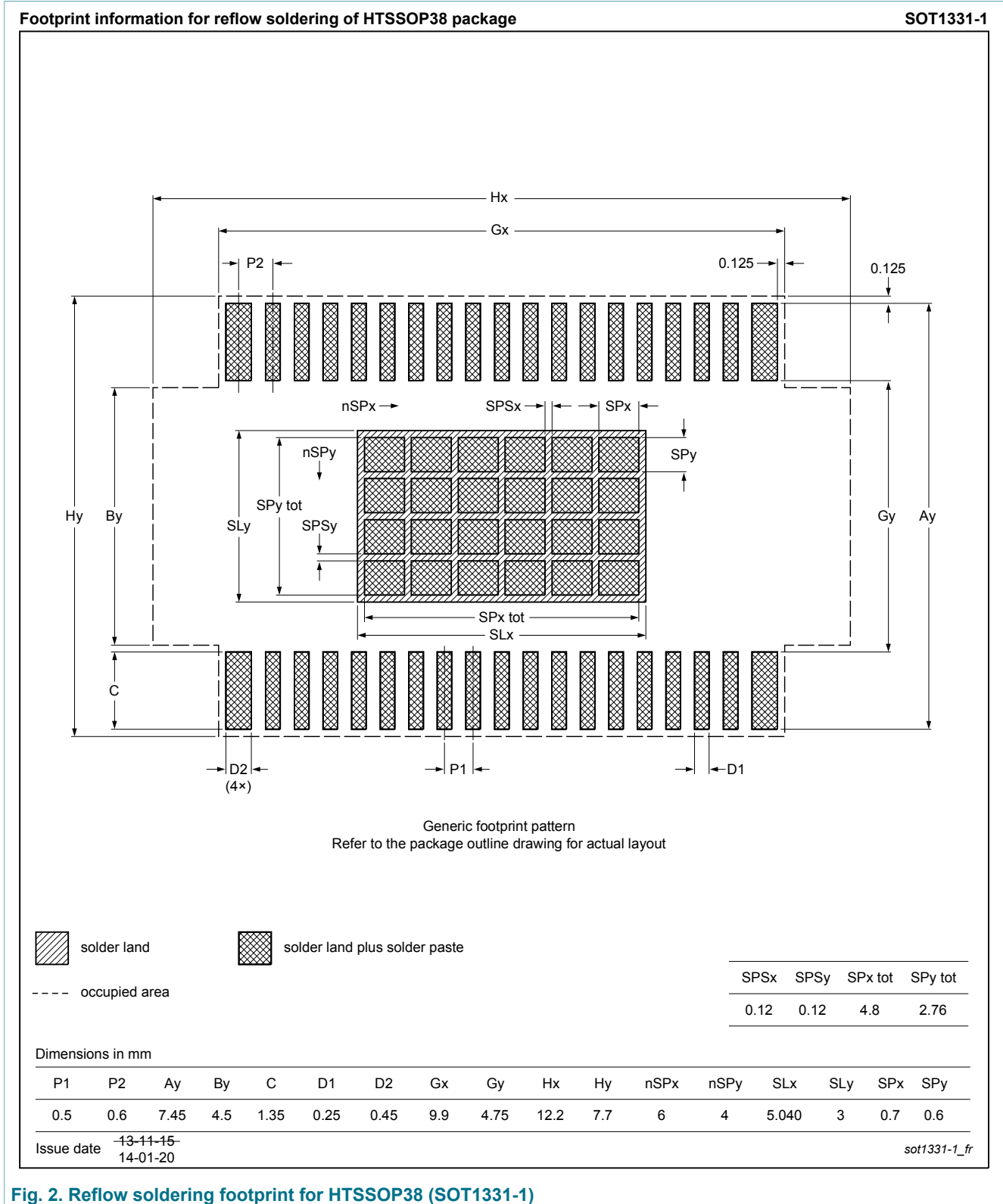


Fig. 2. Reflow soldering footprint for HTSSOP38 (SOT1331-1)

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4. Legal information

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